

# Mechanical and Vibration Testing of Carbon Fiber Composite Material with Embedded Piezoelectric Sensors

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# Background





#### Idea:

- Use piezoelectric sensors and actuators as part of active vibration control of composite fan blades
- Embed the piezoelectric elements into the composite material
- Question:
  - How does the inclusion of packaged piezoelectric elements into composites affect the strength?

#### Previous Research:

- Generally full inclusion of piezo into composite:
  - Warkentin and Crawley (1991) embedded silicon chips
  - Bronowicki et al. (1996) tension, compression, temperature, fatigue
  - Mall et al. (1998, 2000) tension, electromechanical fatigue
  - Paget and Levin (1999) tension and compression
  - Lin and Chang (2002) fabrication techniques; tension, compression, shear, quasi-static impact
  - Konka et al. (2012) foam sandwich structures, flexible piezoelectric elements; tension, bending, short beam shear
- Our goal Determine localized strength of the composite with embedded piezoelectric elements



# Approach

- Embed off-the-shelf piezoelectric sensors into carbon fiber composite material
- ✓ Mechanical Testing
  - 4-Point Bending
  - Short Beam Shear
  - Flatwise Tension
- ✓ Vibration Sensor Testing
  - Effect of curing temperature and pressure on sensor
- Application to composite fan blades
  - Active vibration control:
    - Spin testing with surface-mounted piezoelectric elements in small subscale fan blades
    - Vibration testing with embedded piezoelectric elements in larger subscale fan blades



#### **Materials**

Composite Material	Туре	Description	
Polymer matrix fiber composite	HexPly 8551-7 with IM 7 carbon fibers	Epoxy resin with unidirectional carbon fibers, ply stack-up	
Piezoelectric Elements	Туре	Description	
Monolithic	Non-flexible, PZT-5A, solid material	250µm (0.010") thick PZT	
Flexible-1	Flexible, PZT-5A, rectangular fibers	175μm (0.007") thick PZT fibers	
Flexible-2	Flexible, PZT-5A, circular fibers	250μm (0.010") thick PZT fibers	



# **Mechanical Test Specimen Preparation**









#### **Mechanical Testing**





# **Mechanical Testing**

Test Type	Standard	Specimen Dimensions	Piezoelectric Location	
4-Point Bending	ASTM D7264	165 mm x 12.7 mm x 4.72 mm (6.5" x 0.5" x 0.186")	Two patches, piezo surface 0.3 mm (0.012") below PMFC surface	
Short Beam	ASTM	76 mm x 25 mm x 12.7mm	One patch	
Shear	D2344	(3.0" x 1.0" x 0.5")	located at midplane	
Flatwise	ASTM	22 mm diameter x 20 mm thick	One patch	
Tension	D7291	(0.88" dia. x 0.78" thick)	located at midplane	



#### **4-Point Bending**

#### Baseline





#### Embedded







#### **4-Point Bending**











#### **4-Point Bending**





#### **Short Beam Shear**





#### **Short Beam Shear**





#### **Flatwise Tension**



# piezoelectric fiber

#### Failure within patch at interface

#### Failure within patch at piezoelectric







#### **Flatwise Tension**





#### **Vibration Testing**



Beam Dimensions (Beyond Clamp)	Patch Dimensions	Patch Properties	Patch Sensitivity	Configuration ID	Embedding Depth
191 mm (7.5") long 33.0 mm (1.3") wide 5.66 mm (0.223") thick	28.0 mm x 14.0 mm (1.10" x 0.55")	C = 25 nF E = 30.3 GPa d <sub>31</sub> = -210 pC/N	10x10 <sup>-6</sup> m/m/V	Flexible-1-1	0.3 mm (0.012") deep
				Flexible-1-2	1.5 mm (0.060") deep



#### **Vibration Testing**





# Conclusions

- Mechanical Testing
  - 4-Point Bending 31-47% reduction in strength
  - Short Beam Shear 19-29% reduction in strength
  - Flatwise Tension 83-85% reduction in strength
- Vibration Testing
  - Curing process did not adversely affect sensing ability
- Improving Strength
  - Active vibration control will reduce resonant stresses in the structure; however, it may not be adequate to account for the reduced composite strength
  - Perform analysis to better understand stresses in and between composite and piezoelectric elements
  - Investigate embedding techniques to reduce stresses in piezoelectric elements (e.g. interlacing)
  - Develop packaging techniques to increase the strength in piezoelectric elements
- Plans
  - Embed piezoelectric elements into subscale composite fan blade, perform active vibration control of resonant modes